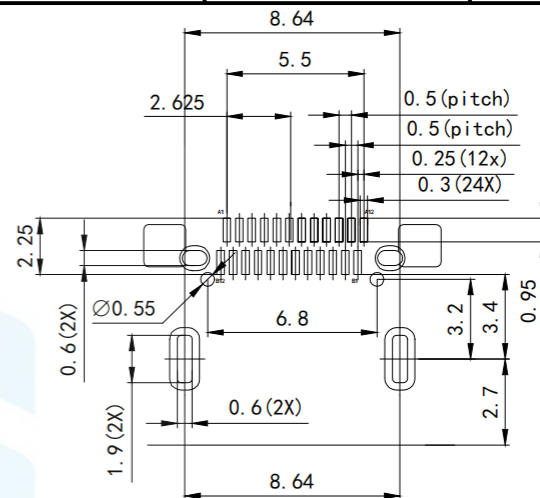
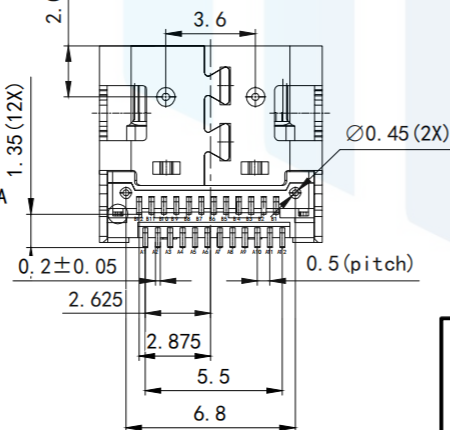
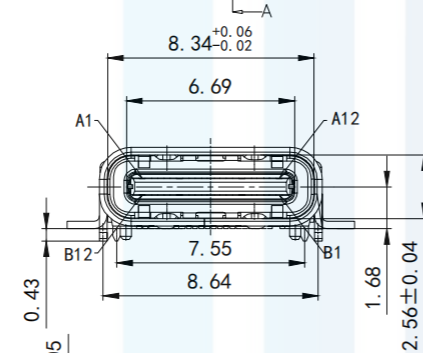
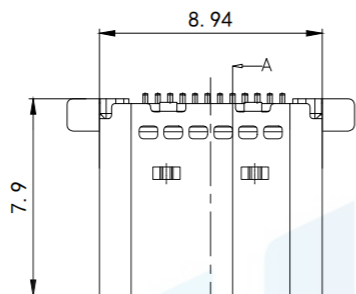


RoHS2.0
Compliant

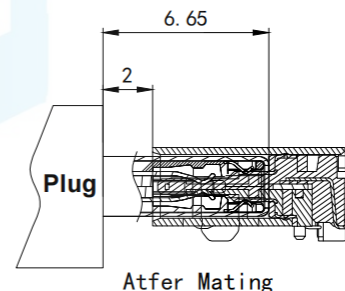
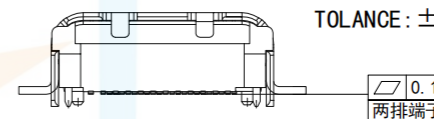


Recommended PCB LAYOUT

TOLANCE: ±0.05

USB TYPE-C PIN ASSIGNMENTS

Pin NO	Signal Name	Pin NO	Signal Name
A1	GND	B12	GND
A2	SSRXP1	B11	SSRXP1
A3	SSRXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN-	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSRXN2
A11	SSRXP2	B2	SSRXP2
A12	GND	B1	GND

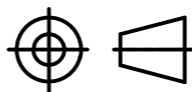


NOTE:
 1. MATERIAL SPECIFICATION:
 1. HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0
 2. CONTACTS: COPPER ALLOY
 3. MID PLATE: STAINLESS STEEL
 4. FRONT SHELL: STAINLESS STEEL
 2. PLATING SPECIFICATION:
 2-1. CONTACTS: Ni 50U" MIN. UNDER PLATED OVER ALL. AU PLATED ON THE FUNCTIONAL AREA OF CONTACT (GOLD PLATING THICKNESS FOLLOW THE P/N) PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 2-2. FRONT SHELL:
 Ni 30U" MIN. UNDER PLATED OVER ALL.
 2-3. SHIELD PLATE&EMI PLATE:
 CLEAR ONLY
 3. MECHANICAL PERFORMANCE
 3-1. INSERTION FORCE: 0.5~2.0kgf.
 3-2. REMOVAL FORCE: 0.8kgf~2.0kgf.
 3-3. DURABILITY: 10000 CYCLES
 4. ELECTRICAL PERFORMANCE,
 4-1. CURRENT RATING: 5.0A VOLTAGE RATING: 5.0V
 4-2. LLCR: VBUS & GND PINS AND OTHER
 PINS: 40mΩ / PIN MAXSHIELD: 50m2 / MAXLLCR
 MAX. CHANGE OF ALL PINS: 10m2.
 4-3. INSULATION RESISTANCE: 100MMIN
 4-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE ENVIRONMENTAL PERFORMANCE:
 5. OPERATING TEMPERATURE: -25'C~+85'C.
 6. IR REFLOW: THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260'C.
 7. SALT SPRAY TEST: 48H

TOLERANCE

X. XXX	±0.05
X. XX	±0.15
X. X	±0.20
X.	±0.30
ANGLE	±5.0°

PROTECTON



东莞市恒祺电子科技有限公司

Dongguan Hengqi Electronic Technology Co., Ltd

<https://www.hq-dz.com>

phone: 15812872448

TITLE:

TYPE C 24P端子SMT前插后贴L=7.9

PART NO: TYPE-C24P-BS028

DRAWING NO: 8.94*7.9*3.16

DRAWN:

DATE:

18-10-08

UNIT:
mm

CHECKED:

DATE:

18-10-08

SCALE:
FULL

APPROVED:

DATE:

18-10-08

SIZE:
A4